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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

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Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f66k90t-i-pt

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

NOTES:



D' N	Pin Number	Pin	Buffer		
Pin Name	QFN/TQFP	Туре	Туре	Description	
				PORTG is a bidirectional I/O port.	
RG0/ECCP3/P3A RG0 ECCP3 P3A	3	I/O I/O O	ST ST	Digital I/O. Capture 3 input/Compare 3 output/PWM3 output. ECCP3 PWM Output A.	
RG1/TX2/CK2/AN19/ C3OUT RG1 TX2 CK2 AN19 C3OUT	4	I/O O I/O I O	ST — ST Analog —	Digital I/O. USART asynchronous transmit. USART synchronous clock (see related RX2/DT2). Analog Input 19. Comparator 3 output.	
RG2/RX2/DT2/AN18/ C3INA RG2 RX2 DT2 AN18 C3INA	5	I/O I I/O I	ST ST ST Analog Analog	Digital I/O. EUSART asynchronous receive. EUSART synchronous data (see related TX2/CK2). Analog Input 18. Comparator 3 Input A.	
RG3/CCP4/AN17/P3D/ C3INB RG3 CCP4 AN17 P3D C3INB	6	I/O I/O I O I	ST S/T Analog — Analog	Digital I/O. Capture 4 input/Compare 4 output/PWM4 output. Analog Input 18. ECCP3 PWM Output D. Comparator 3 Input B.	
RG4/SEG26/RTCC/ T7CKI/T5G/CCP5/AN16/ P1D/C3INC RG4 SEG26 RTCC T7CKI ⁽³⁾ T5G CCP5 AN16 P1D C3INC	8	I/O O I I/O I O I	ST Analog ST ST ST Analog Analog	Digital I/O. SEG26 output for LCD. RTCC output Timer7 clock input. Timer5 external clock gate input. Capture 5 input/Compare 5 output/PWM5 output. Analog Input 16. ECCP1 PWM Output D. Comparator 3 Input C.	
RG5	7			See the MCLR/RG5 pin.	
Legend:TTL= TTL compatible inputCMOS = CMOS compatible input or outputST= Schmitt Trigger input with CMOS levelsAnalog = Analog input					
I= InputO= OutputP= PowerOD= Open-Drain (no P diode to VDD)					

TABLE 1-3 PIC18E6XK90 PINOUT I/O DESCRIPTIONS (CONTINUED)

P = Power $I^2C^{TM} = I^2C/SMBus$

Note 1: Default assignment for ECCP2 when the CCP2MX Configuration bit is set.

2: Alternate assignment for ECCP2 when the CCP2MX Configuration bit is cleared.

3: Not available on PIC18F65K90 and PIC18F85K90 devices.

FIGURE 3-7: PLL BLOCK DIAGRAM



3.5.2.2 PLL and HF-INTOSC

The PLL is available to the internal oscillator block when the internal oscillator block is configured as the primary clock source. In this configuration, the PLL is enabled in software and generates a clock output of up to 64 MHz.

The operation of INTOSC with the PLL is described in **Section 3.6.2 "INTPLL Modes**". Care should be taken that the PLL is enabled only if the HF-INTOSC postscaler is configured for 8 MHz or 16 MHz.

3.6 Internal Oscillator Block

The PIC18F87K90 family of devices includes an internal oscillator block which generates two different clock signals. Either clock can be used as the micro-controller's clock source, which may eliminate the need for an external oscillator circuit on the OSC1 and/or OSC2 pins.

The internal oscillator consists of three blocks, depending on the frequency of operation. They are HF-INTOSC, MF-INTOSC and LF-INTRC.

In HF-INTOSC mode, the internal oscillator can provide a frequency, ranging from 31 kHz to 16 MHz, with the postscaler deciding the selected frequency (IRCF<2:0>).

The INTSRC bit (OSCTUNE<7>) and MFIOSEL bit (OSCCON2<0>) also decide which INTOSC provides the lower frequency (500 kHz to 31 kHz). For the HF-INTOSC to provide these frequencies, INTSRC = 1 and MFIOSEL = 0.

In HF-INTOSC, the postscaler (IRCF<2:0>) provides the frequency range of 31 kHz to 16 MHz. If HF-INTOSC is used with the PLL, the input frequency to the PLL should be 8 MHz or 16 MHz (IRCF<2:0> = 111, 110).

For MF-INTOSC mode to provide a frequency range of 500 kHz to 31 kHz, INTSRC = 1 and MFIOSEL = 1. The postscaler (IRCF<2:0>), in this mode, provides the frequency range of 31 kHz to 500 kHz.

The LF-INTRC can provide only 31 kHz if INTSRC = 0.

The LF-INTRC provides 31 kHz and is enabled if it is selected as the device clock source. The mode is enabled automatically when any of the following is enabled:

- Power-up Timer
- · Fail-Safe Clock Monitor
- · Watchdog Timer
- · Two-Speed Start-up

These features are discussed in greater detail in Section 28.0 "Special Features of the CPU".

The clock source frequency (HF-INTOSC, MF-INTOSC or LF-INTRC direct) is selected by configuring the IRCF bits of the OSCCON register, as well the INTSRC and MFIOSEL bits. The default frequency on device Resets is 8 MHz.

3.6.1 INTIO MODES

Using the internal oscillator as the clock source eliminates the need for up to two external oscillator pins, which can then be used for digital I/O. Two distinct oscillator configurations, which are determined by the OSC Configuration bits, are available:

- In INTIO1 mode, the OSC2 pin (RA6) outputs Fosc/4, while OSC1 functions as RA7 (see Figure 3-8) for digital input and output.
- In INTIO2 mode, OSC1 functions as RA7 and OSC2 functions as RA6 (see Figure 3-9). Both are available as digital input and output ports.

FIGURE 3-8: INTIO1 OSCILLATOR MODE



FIGURE 3-9: INTIO2 OSCILLATOR MODE



TABLE 11-8: 5	SUMMARY OF REGISTERS ASSOCIATED WITH PORTD
---------------	--

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
PORTD	RD7	RD6	RD5	RD4	RD3	RD2	RD1	RD0	78
LATD	LATD7	LATD6	LATD5	LATD4	LATD3	LATD2	LATD1	LATD0	78
TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	78
LCDSE0	SE07	SE06	SE05	SE04	SE03	SE02	SE01	SE00	83
PADCFG1	RDPU	REPU	RJPU ⁽¹⁾		_	RTSECSEL1	RTSECSEL0	_	80

Legend: Shaded cells are not used by PORTD.

Note 1: This bit is not available in 64-pin devices.

NOTES:

15.3 Timer3/5/7 16-Bit Read/Write Mode

Timer3/5/7 can be configured for 16-bit reads and writes (see Figure 15.3). When the RD16 control bit (TxCON<1>) is set, the address for TMRxH is mapped to a buffer register for the high byte of Timer3/5/7. A read from TMRxL will load the contents of the high byte of Timer3/5/7 into the Timerx High Byte Buffer register. This provides users with the ability to accurately read all 16 bits of Timer3/5/7 without having to determine whether a read of the high byte, followed by a read of the low byte, has become invalid due to a rollover between reads.

A write to the high byte of Timer3/5/7 must also take place through the TMRxH Buffer register. The Timer3/ 5/7 high byte is updated with the contents of TMRxH when a write occurs to TMRxL. This allows users to write all 16 bits to both the high and low bytes of Timer3/5/7 at once.

The high byte of Timer3/5/7 is not directly readable or writable in this mode. All reads and writes must take place through the Timerx High Byte Buffer register.

Writes to TMRxH do not clear the Timer3/5/7 prescaler. The prescaler is only cleared on writes to TMRxL.

15.4 Using the SOSC Oscillator as the Timer3/5/7 Clock Source

The SOSC internal oscillator may be used as the clock source for Timer3/5/7. The SOSC oscillator is enabled by setting one of five bits: any of the four SOSCEN bits in the TxCON registers (TxCON<3>) or the SOSCGO bit in the OSCCON2 register (OSCCON2<3>). To use it as the Timer3/5/7 clock source, the TMRxCS bit must also be set. As previously noted, this also configures Timer3/5/7 to increment on every rising edge of the oscillator source.

The SOSC oscillator is described in Section 13.0 "Timer1 Module".

15.5 Timer3/5/7 Gates

Timer3/5/7 can be configured to count freely or the count can be enabled and disabled using the Timer3/ 5/7 gate circuitry. This is also referred to as the Timer3/5/7 gate count enable.

The Timer3/5/7 gate can also be driven by multiple selectable sources.

TIMER3/5/7 GATE COUNT ENABLE 15.5.1

The Timerx Gate Enable mode is enabled by setting the TMRxGE bit (TxGCON<7>). The polarity of the Timerx Gate Enable mode is configured using the TxGPOL bit (TxGCON<6>).

When Timerx Gate Enable mode is enabled, Timer3/5/7 will increment on the rising edge of the Timer3/5/7 clock source. When Timerx Gate Enable mode is disabled, no incrementing will occur and Timer3/5/7 will hold the current count. See Figure 15-2 for timing details.

TABLE 15-1:	TIMER3/5/7 GATE ENABLE
	SELECTIONS

TxCLK ^(†)	TxGPOL (TxGCON<6>)	TxG Pin	Timerx Operation
\uparrow	0	0	Counts
\uparrow	0	1	Holds Count
1	1	0	Holds Count
	1	1	Counts

† The clock on which TMR3/5/7 is running. For more information, see TxCLK in Figure 15-1.



FIGURE 15-2: TIMER3/5/7 GATE COUNT ENABLE MODE

20.3.2 INTERNAL RESISTOR BIASING

This mode does not use external resistors, but rather internal resistor ladders that are configured to generate the bias voltage.

The internal reference ladder actually consists of three separate ladders. Disabling the internal reference ladder disconnects all of the ladders, allowing external voltages to be supplied.

Depending on the total resistance of the resistor ladders, the biasing can be classified as low, medium or high power. Table 20-3 shows the total resistance of each of the ladders. Figure 20-4 shows the internal resister ladder connections. When the internal resistor ladder is selected, the bias voltage can either be from VDD or from VDDCORE, depending on the LCDIRS setting.

TABLE 20-3: INTERNAL RESISTANCE LADDER POWER MODES

Power Mode	Nominal Resistance of Entire Ladder	ldd
Low	3 ΜΩ	1 μA
Medium	300 kΩ	10 μA
High	30 kΩ	100 μA

FIGURE 20-4: LCD BIAS INTERNAL RESISTOR LADDER CONNECTION DIAGRAM



20.7 LCD Frame Frequency

The rate at which the COM and SEG outputs change is called the LCD frame frequency.

TABLE 20-5: FRAME FREQUENCY FORMULAS

Multiplex	Frame Frequency =				
Static	Clock Source/(4 x 1 x (LP<3:0> + 1))				
1/2	Clock Source/(2 x 2 x (LP<3:0> + 1))				
1/3	Clock Source/(1 x 3 x (LP<3:0> + 1))				
1/4	Clock Source/(1 x 4 x (LP<3:0> + 1))				

Note: Clock source is (Fosc/4)/8192, Timer1 Osc/32 or INTRC/32.

TABLE 20-6: APPROXIMATE FRAME FREQUENCY (IN Hz) USING Fosc AT 32 MHz, TIMER1 AT 32.768 kHz OR INTRC OSC

LP<3:0>	Static	1/2	1/3	1/4
1	125	125	167	125
2	83	83	111	83
3	62	62	83	62
4	50	50	67	50
5	42	42	56	42
6	36	36	48	36
7	31	31	42	31

20.8 LCD Waveform Generation

LCD waveform generation is based on the philosophy that the net AC voltage across the dark pixel should be maximized and the net AC voltage across the clear pixel should be minimized. The net DC voltage across any pixel should be zero.

The COM signal represents the time slice for each common, while the SEG contains the pixel data.

The pixel signal (COM-SEG) will have no DC component and can take only one of the two rms values. The higher rms value will create a dark pixel and a lower rms value will create a clear pixel.

As the number of commons increases, the delta between the two rms values decreases. The delta represents the maximum contrast that the display can have.

The LCDs can be driven by two types of waveforms: Type-A and Type-B. In a Type-A waveform, the phase changes within each common type, whereas a Type-B waveform's phase changes on each frame boundary. Thus, Type-A waveforms maintain 0 VDc over a single frame, whereas Type-B waveforms take two frames.

Note 1:	If Sleep has to be executed with
	LCD Sleep enabled (SLPEN
	(LCDCON<6>) = 1), care must be taken
	to execute Sleep only when VDC on all
	the pixels is '0'.
2:	When the LCD clock source is (Fosc/4)/

2: When the LCD clock source is (FOSC/4)/ 8192, if Sleep is executed irrespective of the LCDCON<SLPEN> setting, the LCD goes into Sleep. Thus, take care to see that VDC on all pixels is '0' when Sleep is executed.

Figure 20-7 through Figure 20-17 provide waveforms for static, half-multiplex, one-third multiplex and quarter multiplex drives for Type-A and Type-B waveforms.

21.3.1 REGISTERS

Each MSSP module has four registers for SPI mode operation. These are:

- MSSPx Control Register 1 (SSPxCON1)
- MSSPx Status Register (SSPxSTAT)
- Serial Receive/Transmit Buffer Register (SSPxBUF)
- MSSPx Shift Register (SSPxSR) Not directly accessible

SSPxCON1 and SSPxSTAT are the control and status registers in SPI mode operation. The SSPxCON1 register is readable and writable. The lower 6 bits of the SSPxSTAT are read-only. The upper two bits of the SSPxSTAT are read/write.

SSPxSR is the shift register used for shifting data in or out. SSPxBUF is the buffer register to which data bytes are written to or read from. In receive operations, SSPxSR and SSPxBUF together create a double-buffered receiver. When SSPxSR receives a complete byte, it is transferred to SSPxBUF and the SSPxIF interrupt is set.

During transmission, the SSPxBUF is not double-buffered. A write to SSPxBUF will write to both SSPxBUF and SSPxSR.

Note: The SSPxBUF register cannot be used with read-modify-write instructions, such as BCF, COMF, etc.
 To avoid lost data in Master mode, a read of the SSPxBUF must be performed to clear the Buffer Full (BF) detect bit (SSPxSTAT<0>) between each transmission.

REGISTER 21-1: SSPxSTAT: MSSPx STATUS REGISTER (SPI MODE)

				-	-		
R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE ⁽¹⁾	D/Ā	Р	S	R/W	UA	BF
bit 7							bit 0
Legend:							

Logona.			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	SMP: Sample bit
	SPI Master mode:
	1 = Input data sampled at the end of data output time
	0 = Input data sampled at the middle of data output time
	SPI Slave mode:
	SMP must be cleared when SPI is used in Slave mode.
bit 6	CKE: SPI Clock Select bit ⁽¹⁾
	1 = Transmit occurs on transition from active to Idle clock state
	0 = Transmit occurs on transition from Idle to active clock state
bit 5	D/A: Data/Address bit
	Used in I ² C [™] mode only.
bit 4	P: Stop bit
	Used in I ² C mode only. This bit is cleared when the MSSPx module is disabled; SSPEN is cleared.
bit 3	S: Start bit
	Used in I ² C mode only.
bit 2	R/W: Read/Write Information bit
	Used in I ² C mode only.
bit 1	UA: Update Address bit
	Used in I ² C mode only.
bit 0	BF: Buffer Full Status bit (Receive mode only)
	1 = Receive complete, SSPxBUF is full
	0 = Receive not complete, SSPxBUF is empty

Note 1: Polarity of the clock state is set by the CKP bit (SSPxCON1<4>).

21.3.4 ENABLING SPI I/O

To enable the serial port, MSSP Enable bit, SSPEN (SSPxCON1<5>), must be set. To reset or reconfigure SPI mode, clear the SSPEN bit, reinitialize the SSPxCON registers and then set the SSPEN bit. This configures the SDIx, SDOx, SCKx and SSx pins as serial port pins. For the pins to behave as the serial port function, some must have their data direction bits (in the TRIS register) appropriately programmed as follows:

- SDIx must have TRISC<4> or TRISD<5> bit set
- SDOx must have the TRISC<5> or TRISD<4> bit cleared
- SCKx (Master mode) must have the TRISC<3> or TRISD<6>bit cleared
- SCKx (Slave mode) must have the TRISC<3> or TRISD<6> bit set
- SSx must have the TRISF<7> or TRISD<7> bit set

Any serial port function that is not desired may be overridden by programming the corresponding Data Direction (TRIS) register to the opposite value.

21.3.5 TYPICAL CONNECTION

Figure 21-2 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCKx signal. Data is shifted out of both shift registers on their programmed clock edge and latched on the opposite edge of the clock. Both processors should be programmed to the same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application software. This leads to three scenarios for data transmission:

- · Master sends data Slave sends dummy data
- Master sends data Slave sends data
- Master sends dummy data Slave sends data

FIGURE 21-2: SPI MASTER/SLAVE CONNECTION



21.4.17.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

- a) A low level is sampled on SDAx when SCLx goes from a low level to a high level.
- b) SCLx goes low before SDAx is asserted low, indicating that another master is attempting to transmit a data '1'.

When the user deasserts SDAx and the pin is allowed to float high, the BRG is loaded with SSPxADD<6:0> and counts down to 0. The SCLx pin is then deasserted and when sampled high, the SDAx pin is sampled.

If SDAx is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0', Figure 21-31). If SDAx is sampled high, the BRG is reloaded and begins counting. If SDAx goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDAx at exactly the same time.

If SCLx goes from high-to-low before the BRG times out and SDAx has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition (see Figure 21-32).

If, at the end of the BRG time-out, both SCLx and SDAx are still high, the SDAx pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCLx pin, the SCLx pin is driven low and the Repeated Start condition is complete.

FIGURE 21-31: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)



FIGURE 21-32: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



EXAMPLE 22-1: CALCULATING BAUD RATE ERROR

For a device with Fosc of 16	6 MH	z, desired baud rate of 9600, Asynchronous mode, and 8-bit BRG:						
Desired Baud Rate	=	Fosc/(64 ([SPBRGHx:SPBRGx] + 1))						
Solving for SPBRGHx:SPBRGx:								
Х	=	((FOSC/Desired Baud Rate)/64) - 1						
	=	((16000000/9600)/64) – 1						
	=	[25.042] = 25						
Calculated Baud Rate	=	1600000/(64 (25 + 1))						
	=	9615						
Error	=	(Calculated Baud Rate - Desired Baud Rate)/Desired Baud Rate						
	=	(9615 - 9600)/9600 = 0.16%						

TABLE 22-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:	
TXSTA1	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	77	
RCSTA1	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	77	
BAUDCON1	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN	79	
SPBRGH1	EUSART1 Baud Rate Generator Register High Byte									
SPBRG1	EUSART1	Baud Rate	Generator I	Register Lo	w Byte				77	
TXSTA2	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	81	
RCSTA2	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	81	
BAUDCON2	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	_	WUE	ABDEN	81	
SPBRGH2	EUSART2 Baud Rate Generator Register High Byte									
SPBRG2	EUSART2	Baud Rate	Generator I	Register Lo	w Byte				82	

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the BRG.

22.4.2 EUSART SYNCHRONOUS SLAVE RECEPTION

The operation of the Synchronous Master and Slave modes is identical, except in the case of Sleep, or any Idle mode, and bit, SREN, which is a "don't care" in Slave mode.

If receive is enabled by setting the CREN bit prior to entering Sleep or any Idle mode, then a word may be received while in this low-power mode. Once the word is received, the RSR register will transfer the data to the RCREGx register. If the RCxIE enable bit is set, the interrupt generated will wake the chip from the low-power mode. If the global interrupt is enabled, the program will branch to the interrupt vector. To set up a Synchronous Slave Reception:

- 1. Enable the synchronous master serial port by setting bits, SYNC and SPEN, and clearing bit, CSRC.
- 2. If interrupts are desired, set enable bit, RCxIE.
- 3. If 9-bit reception is desired, set bit, RX9.
- 4. To enable reception, set enable bit, CREN.
- 5. Flag bit, RCxIF, will be set when reception is complete. An interrupt will be generated if enable bit, RCxIE, was set.
- Read the RCSTAx register to get the 9th bit (if enabled) and determine if any error occurred during reception.
- 7. Read the 8-bit received data by reading the RCREGx register.
- 8. If any error occurred, clear the error by clearing bit, CREN.
- If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	75
PIR1	—	ADIF	RC1IF	TX1IF	SSP1IF	TMR1GIF	TMR2IF	TMR1IF	77
PIE1	_	ADIE	RC1IE	TX1IE	SSP1IE	TMR1GIE	TMR2IE	TMR1IE	77
IPR1	—	ADIP	RC1IP	TX1IP	SSP1IP	TMR1GIP	TMR2IP	TMR1IP	77
PIR3	TMR5GIF	LCDIF	RC2IF	TX2IF	CTMUIF	CCP2IF	CCP1IF	RTCCIF	77
PIE3	TMR5GIE	LCDIE	RC2IE	TX2IE	CTMUIE	CCP2IE	CCP1IE	RTCCIE	77
IPR3	TMR5GIP	LCDIP	RC2IP	TX2IP	CTMUIP	CCP2IP	CCP1IP	RTCCIP	77
RCSTA1	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	77
RCREG1	EUSART1	Receive Re	gister						77
TXSTA1	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	77
BAUDCON1	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	_	WUE	ABDEN	79
SPBRGH1	EUSART1	Baud Rate (Generator R	egister High	n Byte				76
SPBRG1	EUSART1	Baud Rate (Generator R	egister Low	v Byte				77
RCSTA2	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	81
RCREG2	EUSART2	Receive Re	gister						82
TXSTA2	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	81
BAUDCON2	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16		WUE	ABDEN	81
SPBRGH2	EUSART2	Baud Rate (Generator R	egister High	n Byte				82
SPBRG2	EUSART2	Baud Rate (Generator R	egister Low	v Byte				82

TABLE 22-10: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Legend: — = unimplemented, read as '0'. Shaded cells are not used for synchronous slave reception.

26.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

The PIC18F87K90 family of devices has a High/Low-Voltage Detect module (HLVD). This is a programmable circuit that sets both a device voltage trip point and the direction of change from that point. If the device experiences an excursion past the trip point in that direction, an interrupt flag is set. If the interrupt is enabled, the program execution branches to the interrupt vector address and the software responds to the interrupt. The High/Low-Voltage Detect Control register (Register 26-1) completely controls the operation of the HLVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

The module's block diagram is shown in Figure 26-1.

REGISTER 26-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

RMAG: Vo Event occu Event occu VST: Band	IRVST W = Writable k '1' = Bit is set Itage Direction urs when voltag	HLVDEN bit n Magnitude S ge equals or o	U = Unimplen '0' = Bit is cle Select bit exceeds trip po	HLVDL2 ⁽¹⁾ nented bit, read ared	HLVDL1 ⁽¹⁾ as '0' x = Bit is unkr	HLVDL0 ⁽¹⁾ bit 0									
RMAG: Vo Event occu Event occu VST: Band	W = Writable t '1' = Bit is set Itage Direction urs when voltag	bit n Magnitude S ge equals or o ge equals or f	U = Unimplen '0' = Bit is cle Select bit exceeds trip po	nented bit, read ared	as '0' x = Bit is unkr	bit 0									
RMAG: Vo Event occu Event occu VST: Band	W = Writable t '1' = Bit is set Itage Direction urs when voltag	bit n Magnitude S ge equals or o ge equals or f	U = Unimplen '0' = Bit is cle Select bit exceeds trip po	nented bit, read ared	as '0' x = Bit is unkr	nown									
RMAG: Vo Event occu Event occu VST: Band	W = Writable t '1' = Bit is set Itage Direction urs when voltag	bit n Magnitude S ge equals or o ge equals or f	U = Unimplen '0' = Bit is cle Gelect bit exceeds trip po	nented bit, read ared	as '0' x = Bit is unkr	nown									
RMAG: Vo Event occu Event occu VST: Band	W = Writable t '1' = Bit is set ltage Direction urs when voltage Can Peference	h Magnitude S ge equals or o ge equals or f	U = Unimplen '0' = Bit is cle Select bit exceeds trip po	nented bit, read	as '0' x = Bit is unkr	nown									
RMAG: Vo Event occu Event occu VST: Band	'1' = Bit is set Itage Direction urs when voltagurs when voltag	n Magnitude S ge equals or o ge equals or f	'0' = Bit is cle Select bit exceeds trip po	ared	x = Bit is unkr	nown									
RMAG: Vo Event occu Event occu VST: Band	Itage Direction urs when voltagurs when voltag	n Magnitude S ge equals or e ge equals or f	Select bit exceeds trip po												
VST: Band	Can Deference	90 0900.000.	alls below trip	point (HLVDL<3:0 point (HLVDL<3	bit 7 VDIRMAG: Voltage Direction Magnitude Select bit 1 = Event occurs when voltage equals or exceeds trip point (HLVDL<3:0>) 0 = Event occurs when voltage equals or falls below trip point (HLVDL<3:0>)										
BGVST: Band Gap Reference Voltages Stable Status Flag bit 1 = Internal band gap voltage references are stable 0 = Internal band gap voltage references are not stable															
 IRVST: Internal Reference Voltage Stable Flag bit 1 = Indicates that the voltage detect logic will generate the interrupt flag at the specified voltage range 0 = Indicates that the voltage detect logic will not generate the interrupt flag at the specified voltage range and the HI VD interrupt should not be enabled 															
HLVDEN: High/Low-Voltage Detect Power Enable bit 1 = HLVD is enabled 0 = HLVD is disabled															
/DL<3:0>: 1 = Extern 0 = Maxim	Voltage Detec al analog inpur um setting	tion Limit bits t is used (inpu	(1) ut comes from t	the HLVDIN pin)										
/	HLVD is e HLVD is d DL<3:0>: 1 = Extern 0 = Maxim	HLVD is enabled HLVD is disabled DL<3:0>: Voltage Detect 1 = External analog inpu 0 = Maximum setting	HLVD is enabled HLVD is disabled DL<3:0>: Voltage Detection Limit bits 1 = External analog input is used (input) 0 = Maximum setting	HLVD is enabled HLVD is disabled DL<3:0>: Voltage Detection Limit bits ⁽¹⁾ 1 = External analog input is used (input comes from 5 0 = Maximum setting	HLVD is enabled HLVD is disabled DL<3:0>: Voltage Detection Limit bits ⁽¹⁾ 1 = External analog input is used (input comes from the HLVDIN pin 0 = Maximum setting	HLVD is enabled HLVD is disabled DL<3:0>: Voltage Detection Limit bits ⁽¹⁾ 1 = External analog input is used (input comes from the HLVDIN pin) 0 = Maximum setting									



REGISTER 28-14: DEVID1: DEVICE ID REGISTER 1 FOR THE PIC18F87K90 FAMILY

R	R	R	R	R	R	R	R
DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5	DEV<2:0>: Device ID bits						
	Devices with DEV<10:3> of 0101 0010 (see DEVID2):						
	010 = PIC18F65K90						
	000 = PIC18F66K90						
	101 = PIC18F85K90						
	011 = PIC18F86K90						
	Devices with DEV<10:3> of 0101 0001:						
	000 = PIC18F67K90						
	010 = PIC18F87K90						
bit 4-0	REV<4:0>: Revision ID bits						
	These bits are used to indicate the device revision.						

REGISTER 28-15: DEVID2: DEVICE ID REGISTER 2 FOR THE PIC18F87K90 FAMILY

R	R	R	R	R	R	R	R	
DEV10 ⁽¹⁾	DEV9 ⁽¹⁾	DEV8 ⁽¹⁾	DEV7 ⁽¹⁾	DEV6 ⁽¹⁾	DEV5 ⁽¹⁾	DEV4 ⁽¹⁾	DEV3 ⁽¹⁾	
bit 7						•	bit 0	
Legend:								
R = Readable bit W = Writable bit			U = Unimplemented bit, read as '0'					
-n = Value at POR '1' = Bit is set			'0' = Bit is cleared x = Bit is unknown					

DEV<10:3>: Device ID bits(1) bit 7-0 These bits are used with the DEV<2:0> bits in the Device ID Register 1 to identify the part number. 0101 0010 = PIC18F65K90, PIC18F66K90, PIC18F85K90 and PIC18F86K90 0101 0001 = PIC18F67K90 and PIC18F87K90

Note 1: These values for DEV<10:3> may be shared with other devices. The specific device is always identified by using the entire DEV<10:0> bit sequence.

INCF	NCFSZ Increment f, Skip if 0		INFS	NZ	Increment f, Skip if Not 0						
Synta	ax:	INCFSZ f {,d {,a}}		Synta	ax:	INFSNZ f {,d {,a}}					
Oper	ands:	$0 \le f \le 255$ $d \in [0, 1]$ $a \in [0, 1]$			Oper	ands:	0 ≤ f ≤ 255 d ∈ [0 , 1] a ∈ [0 , 1]				
Oper	ation:	(f) + 1 \rightarrow de skip if result	est, t = 0		Oper	ation:	(f) + 1 \rightarrow de skip if resul	est, t ≠ 0			
Statu	s Affected: None		Statu	s Affected:	None						
Enco	dina:	0011	11da ff:	ff ffff	Enco	ding:	0100	10da ff:	ff ffff		
Description:		The content incremented placed in W	ts of register 'f d. If 'd' is '0', tl /. If 'd' is '1', th < in register 'f'	" are he result is he result is	Desc	ription:	The conten incremente placed in W placed back	ts of register 'f d. If 'd' is '0', tl /. If 'd' is '1', th k in register 'f'.	l' are he result is he result is		
		If the result which is alro and a NOP i it a two-cycl	is '0', the nex eady fetched i s executed ins le instruction.	t instruction s discarded stead, making			If the result instruction discarded a instead, ma instruction.	is not '0', the which is alread and a NOP is ex aking it a two-c	next dy fetched is xecuted cycle		
		If 'a' is '0', tl If 'a' is '1', tl GPR bank.	he Access Bai he BSR is use	nk is selected. d to select the			If 'a' is '0', t If 'a' is '1', t GPR bank.	he Access Bai he BSR is use	nk is selected. d to select the		
		If 'a' is '0' a set is enabl in Indexed I mode when Section 29 Bit-Oriente Literal Offs	nd the extende ed, this instruct Literal Offset A ever f ≤ 95 (5) .2.3 "Byte-Or d Instruction set Mode" for	ed instruction ction operates Addressing Fh). See iented and s in Indexed details.			If 'a' is '0' a set is enabl in Indexed mode wher Section 29 Bit-Oriente	nd the extended ed, this instruct Literal Offset A lever $f \le 95$ (50 .2.3 "Byte-Oried Instruction set Mode" for	ed instruction ction operates Addressing Fh). See iented and s in Indexed details		
Word	s:	1			Word	s.	1		detano.		
Cycle	Cycles: 1(2) Note: 3 cycles if skip and followed by a 2-word instruction.		Cycle	es:	1(2) Note: 3 cy by a	cles if skip an 2-word instru	d followed Iction.				
QC	cle Activity:	·			QC	vcle Activitv:	,				
	Q1	Q2	Q3	Q4		Q1	Q2	Q3	Q4		
	Decode	Read	Process	Write to		Decode	Read	Process	Write to		
		register 'f'	Data	destination			register 'f'	Data	destination		
lf sk	ip:		~ ~	.	lf sk	ip:					
1	Q1	Q2	Q3	Q4		Q1	Q2	Q3	Q4		
	NO	NO operation	N0 operation	NO		N0 operation	N0 operation	N0 operation	No		
lf sk	ip and followe	d by 2-word in:	struction:	oporation	lfsk	in and followe	d by 2-word in	struction:	operation		
	Q1	Q2	Q3	Q4	II OK		02	03	04		
	No	No	No	No		No	No	No	No		
	operation	operation	operation	operation		operation	operation	operation	operation		
	No	No	No	No		No	No	No	No		
	operation	operation	operation	operation		operation	operation	operation	operation		
<u>Exan</u>	<u>iple:</u>	HERE I NZERO S ZERO S	INCFSZ CN :	IT, 1, 0	Exan	<u>iple:</u>	HERE ZERO NZERO	INFSNZ REG	B, 1, 0		
	Before Instruc	ction				Before Instruc	tion				
	PC	= Address	(HERE)			PC	= Address	(HERE)			
	After Instruction		1))) = REG +	1			
	If CNT	= 0;	I			If REG	≠ 0;				
		= Address	(ZERO)			PC If REG	= Address	(NZERO)			
	PC	<i>→</i> 0,Address	(NZERO)			PC	= Äddress	S (ZERO)			





FIGURE 31-2: VOLTAGE-FREQUENCY GRAPH, REGULATOR DISABLED (INDUSTRIAL/EXTENDED)^(1,2)



DC CH/	ARACTE	ERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended					
Param No.	Sym	Characteristic Min		Тур†	Max	Units	Conditions	
		Internal Program Memory Programming Specifications ⁽¹⁾						
D110	Vpp	Voltage on MCLR/VPP/RE5 pin	VDD + 1.5	—	9	V	(Note 3)	
D113	IDDP	Supply Current during Programming	—	—	10	mA		
		Data EEPROM Memory					(Note 2)	
D120	ED	Byte Endurance	100K	—	—	E/W	-40°C to +125°C	
D121	Vdrw	VDD for Read/Write	1.8	_	5.5	V	Using EECON to read/write ENVREG tied to VDD	
			1.8	—	3.6	V	Using EECON to read/write ENVREG tied to Vss	
D122	TDEW	Erase/Write Cycle Time	—	4	—	ms		
D123	TRETD	Characteristic Retention	40	_	—	Year	Provided no other specifications are violated	
D124	Tref	Number of Total Erase/Write Cycles before Refresh ⁽²⁾	1M	10M	—	E/W	-40°C to +125°C	
		Program Flash Memory						
D130	Eр	Cell Endurance	10K	—	—	E/W	-40°C to +125°C	
D131	Vpr	VDD for Read	1.8	—	5.5	V	ENVREG tied to VDD	
			1.8	—	3.6	V	ENVREG tied to Vss	
D132B	VPEW	Voltage for Self-Timed Erase or Write Operations						
	_	VDD	1.8	_	5.5	V	ENVREG tied to VDD	
D133A	TIW	Self-Timed Write Cycle Time		2	—	ms		
D134	ÎRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated	
D135	IDDP	Supply Current during Programming	—	—	10	mA		
D140	TWE	Writes per Erase Cycle	—	—	1		For each physical address	

TABLE 31-1: MEMORY PROGRAMMING REQUIREMENTS

† Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: These specifications are for programming the on-chip program memory through the use of table write instructions.

2: Refer to Section 8.8 "Using the Data EEPROM" for a more detailed discussion on data EEPROM endurance.

3: The MPLAB[®] ICD 2 does not support variable VPP output. Circuitry to limit the ICD 2 VPP voltage must be placed between the ICD 2 and target system when programming or debugging with the ICD 2.

APPENDIX A: REVISION HISTORY

Revision A (September 2009)

Original data sheet for PIC18F87K90 family devices.

Revision B (April 2010)

Changes to Section 32.0 "Packaging Information", including new packaging diagrams. Changes to some of the values in Section 31.0 "Electrical Characteristics". The new Section 2.0 "Guidelines for Getting Started with PIC18FXXKXX Microcontrollers" has been added. Minor text edits throughout the document.

Revision C (March 2011)

Updated notes for clamping diodes, updated D080, D090, D121, D131 and D310. Also, updated the absolute maximum specification for the I/O pin and the maximum specification for the input/output clamp current. The 64-lead QFN packaging diagram was updated.

Revision D (July 2011)

Updated the specification values in **Section 31.0** "**Electrical Characteristics**". Minor text edits throughout the document.

APPENDIX B: MIGRATION FROM PIC18F85J90 AND PIC18F87J90 TO PIC18F87K90

Devices in the PIC18F87K90, PIC18F85J90 and PIC18F87J90 families are almost similar in their functions and features. Code can be migrated from the 18F85J90 to the PIC18F87K90 without many changes. The differences between the two device families are listed in Table B-1.